

**PAGE 3, FIRST FULL PARAGRAPH**

In another aspect of the present invention, the thermal conductive material comprises an organic material of which melting point transition is in the range of 30-70°C. Therefore, when heat is applied from the electronic component and the temperature of the organic material reaches the melting point transition for example, the organic material gets liquidized. At this time, a filler having high thermal conductivity is evenly dispersed within the liquidized organic material. The thermal conductive material of the present invention then changes its form (plasticizes itself) corresponding to the outer shape of which it comes in contact with and maintains the form thereafter.